

Product Change Notification

The information below reflects a change that is being implemented.

Notice Date: 12/15/2006

Product Category: Power Management

Notification Subject: Change #711 : QUALIFICATION OF 3L SOT-80 PACKAGE AT CEI WITH BARE Cu LEADFRAME AND 2025DSI NON-CONDUCTIVE EPOXY

Notification Body:
Microchip Part#s Affected:
MCP111
MCP112
MCP1700
MCP1702

Description of Change:
New Bill Of Materials

Impacts to Data Sheet:
NONE

Reason for Change:
IMPROVED MANUFACTURABILITY

Estimated Change Implementation Date(s):
JANUARY 31, 2007

Markings to Distinguish Revised From Unrevised Devices: (e.g.: Date Code, Device Marking, Ship Container Marking)
TRACEABILITY CODE
